



## Material Content Data Sheet



Halogen-Free

<b>Sales Product Name</b>	BTN9990LV	<b>Issued</b>	09. February 2022
<b>MA#</b>	MA005547819		
<b>Package</b>	PG-HSOF-7-1	<b>Weight*</b>	347.53 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	0.628	0.18	0.18	1807	1807
chip_2	inorganic material	silicon	7440-21-3	0.867	0.25	0.25	2494	2494
chip_3	inorganic material	silicon	7440-21-3	1.464	0.42	0.42	4213	4213
leadframe	inorganic material	phosphorus	7723-14-0	0.055	0.02		157	
	non noble metal	iron	7439-89-6	0.182	0.05		523	
	non noble metal	copper	7440-50-8	181.611	52.26	52.33	522574	523254
wire	non noble metal	copper	7440-50-8	0.141	0.04	0.04	407	407
encapsulation	inorganic material	zinc oxide	1314-13-2	1.516	0.44		4361	
	miscellaneous	miscellaneous	-	6.063	1.74		17445	
	plastics	epoxy resin	-	22.735	6.54		65418	
	inorganic material	silicon dioxide	60676-86-0	121.252	34.89	43.61	348896	436120
lead finish	non noble metal	tin	7440-31-5	2.025	0.58	0.58	5826	5826
plating	noble metal	silver	7440-22-4	0.271	0.08	0.08	781	781
solder	non noble metal	tin	7440-31-5	0.063	0.02		181	
	noble metal	silver	7440-22-4	0.079	0.02		227	
	non noble metal	lead	7439-92-1	3.010	0.87	0.91	8662	9070
glue	plastics	Polyimide	26023-21-2	0.126	0.04	0.04	362	362
heat sink clip	inorganic material	phosphorus	7723-14-0	0.002			5	
	non noble metal	iron	7439-89-6	0.005			16	
	non noble metal	copper	7440-50-8	5.437	1.56	1.56	15645	15666
*deviation	< 10%	Sum in total:				100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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